

SOM-Trizeps-VII-MX6

SODIMM-200 CPU-Module with NXP i.MX6 Applications Processors

High-performance i.MX6 CPU module with compact dimensions





CPI

NXP i.MX6 Applications Processors, Solo up to QuadCore 42

CONNECTIVITY

1x 100/1000 Megabit Ethernet, WiFi/BT, USB 2.0, PCIe, HDMI®



Vivante GC3500 2D accelerator + Vivante GC2000 3D accelerator



MEMORY

Up to 2 GB LPDDR3-1066 RAM memory, 64 Bit







(I) Available in Industrial Temperature Range





MAIN FIELDS OF APPLICATION

















Coffee & Vending

Medical

Transportation

Industrial Automation Smart Devices

Smart Buldings & Digital Signage Smart Cities Energy & Utilities

FEATURES

	Processor	NXP i.MX M6 Family based on Arm® Cortex®-A9 cores i.MX 6Solo - 1x Cortex®-A9 core up to 1.0GHz i.MX 6DualLite - 2x Cortex®-A9 cores up to 1.0GHz i.MX 6Dual - 2x Cortex®-A9 cores up to 1.0GHz i.MX 8Quad - 4x Cortex®-A9 cores up to 1.0GHz
H	Memory	Soldered down LPDDR3-1066 memory up to 2 GB, 64-bit interface
Š	Graphics	Vivante GC3500 2D Hardware accelerator Vivante GC2000 3D Hardware accelerator, supports OpenGL® ES 2.0 3D Dedicated Vector Graphics accelerator, supports OpenVG TM (only i.MX 6Dual and i.MX 6Quad) Supports up to 3 independent displays with i.MX 6Dual and i.MX 6Quad Supports 2 independent displays with i.MX 6DualLite and i.MX 6Solo
1	Video Interfaces	HDMI® v1.4, 2x LVDS, LCD 24 Bit RGB, MIPI
-23	Video Resolution	LVDS, up to 1920x1200 HDMI®, up to 1080p
9	Mass Storage	Onboard 4 Bit wide μ SD Card Socket or onboard 8 Bit wide eMMC
靐	Networking	1x 100 Mbit Ethernet RGMII PHY or 1000 Mbit Ethernet RGMII interface Optional: WiFi 802.11 a/b/g/n/e/i/h/d/k/r/w, BT 3.0+ EDR
0 ~~	USB	Ix USB 2.0 OTG and Ix USB 2.0 Host
:::::	PCI-e	l x PCI-e
	Audio	AC'97 Audio Codec with 4/5 wires res. Touch and 4x 12 Bit ADC (2x comparator inputs for battery monitoring); Stereo: Line-in, Mic-in, Speaker-out, Headphone out

<u></u> 0	Serial Ports	3x UART
	Other Interfaces	2x FlexCAN S-ATAII 2x 4 Bit wide SDIO RTC SPDIF Adress-Data-Bus 2x I2C 2x SPI GPIOS 2x PWM
	Power Supply	33 V _{DC}
os	Operating System	Linux Android Windows Embedded Compact 7, 2013 Windows 10 IoT Core
<u>[</u>	Operating Temperature*	-40 ÷ 85°C (industrial) -20 ÷ 85°C (Extended Consumer) 0 ÷ 70°C (Consumer)
L	Dimensions	67.6 x 36.7 x 6.4 mm

*All carrier board components must remain within the operating temperature at any and all times, including start-up; carrier operating temperature is independent of the module installed. Please refer to the specific module for more details. Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider specific cooling solutions for the final system.



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DATA ORCHESTRATION

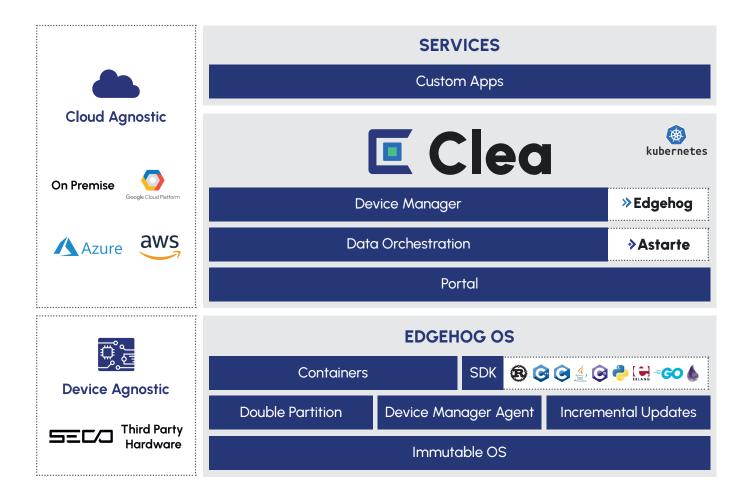
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